



承認書

SPECIFICATION FOR APPROVAL

客 戶：富士康科技股份有限公司

品 名：3.96mm WTB Wafer Conn. T/H S/R S/T Type

客戶料號：

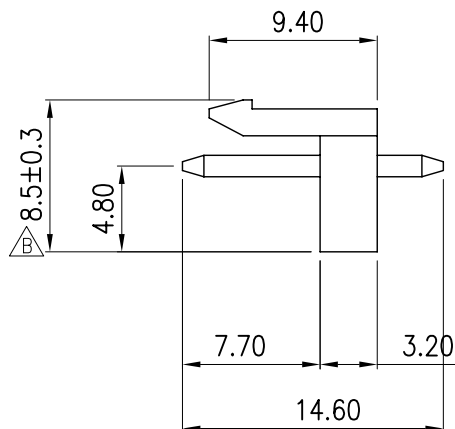
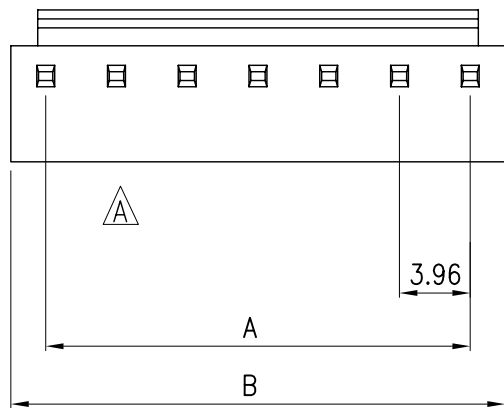
宏致料號：86514-0200

承認日期	
部 門	
承認欄	

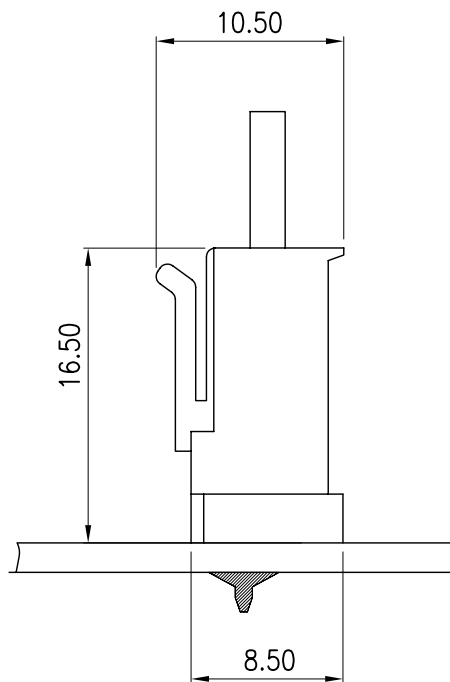
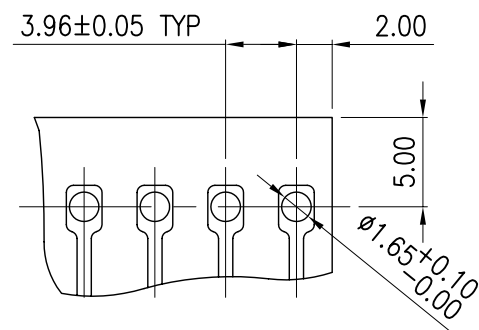
宏致電子股份有限公司
Aces Electronic Co., Ltd.

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業務代表：丁雨祥

日期：2010/8/23



NOTES:
1.MATERIAL:
HOUSING:NYLON 66, UL 94V-0
CONTACT:BRASS
PLATING:TIN OVER NICKEL
△C 2.SPEC. PLS REFER TO 86515-XXXX.



P/N LEGEND
86514-XX00
NO of CKT

CKT	DIM A	DIM B
2	3.96	7.86
3	7.92	11.82
4	11.88	15.78
5	15.84	19.74
6	19.8	23.7
7	23.76	27.66
8	27.72	31.62
9	31.68	35.58
10	35.64	39.54
11	39.6	44
12	43.56	48

(RECOMMENDED PCB LAYOUT)

C	增加NOTE 2.(ECN-0703058)	'07/3/6	Kelly
B	修改公差(ECN-0610105)	'06/10/25	Kelly
A	FOR APR95042 MODIFY(ECN-0605006)	06/5/4	Mandy
O	新圖製成	00/1/6	Grace
REV	REVISION DESCRIPTION	DATE	SIGNATURE

一般公差 TOLERANCES X. ±0.5 .XX ±0.15 .X ±0.25 .XXX ±0.1 ANGLES ±2°		宏致電子股份有限公司 Aces Electronic Co.,Ltd.	
檢驗尺寸標示 SYMBOLS Ⓢ Ⓣ INDICATE CLASSIFICATION DIMENSION		品名 (TITLE) 3.96mm WTB WAFER CONN. T/H S/R S/T TYPE	製圖 (DR) '06/9/12 JASON
Ⓢ MARK IS CRITICAL DIM. Ⓣ MARK IS MAJOR DIM.		圖號 (DWG.NO) 86514-XX00	核准 (APPD) JASON
表面處理 (FINISH)	比例 (SCALE) 2.5:1	單位 (UNITS) mm	張數 (SHEET) 1 OF 1
			SIZE A4
			REV C

Aces Electronic Co., Ltd.

Product Specification

Title : 2.54mm Square Pin Header

Product Specification

PS - 86514

Sheet

1 of 2

Rev

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Product Specification PS - 86514

1. Scope

This specification covers the square pin header, Aces's P/N : 86514-x x x x
Applicable PC Board thickness : 0.63"(1.60 mm)

2. Material

Base : PBT(30% GF) , UL 94-0

Contact : Brass

Contact Plating : 0 : 120u" Tin/Pb over 50u" Ni underplating
 1 : Gold flash over 50u" Ni underplating
 2 : 15u" AV
 3 : 30u" AV

3. Ratings

3.1 Rated Voltage (Max) : AC 250 V, DC 350 V

3.2 Rated Current (Max) : 3 A [AC/DC]

3.3 Temperature Range : - 25 deg C ~ + 85 deg C

4. Performance

4.1 Contact Resistance Initial : 20 milliohms max.
 (Low Level) After conditioning : 40 Mohm max.

4.2 Insulation Resistance 1,000 mega-ohms min.
 initial & following

4.3 Withstanding Voltage 1,000V AC/min.

4.4 Pin Retention Force 1.5 kg min.